Final Product Change Notification

201803021F01

Issue Date: 24-Aug-2018
Effective Date: 21-Nov-2018

Management Summary

MPC8245 and MPC8250/8255/8260/8265 conversion from Glob Top to Center Gate Mold.

Change Category

☐ Wafer Fab Process
☑ Assembly Process
☐ Product Marking
☐ Test Location
☐ Design
☐ Wafer Fab Materials
☑ Assembly Materials
☐ Mechanical Specification
☐ Test Process
☐ Errata
☐ Wafer Fab Location
☐ Assembly Location
☐ Packing/Shipping/Labeling
☐ Test Equipment
☐ Electrical spec./Test coverage
☐ Firmware
☐ Other

MPC8245 and MPC8250/8255/8260/8265 TBGA Product Family Conversion to Center Gate Mold Process

Description of Change

NXP is pleased to announce a new encapsulation process called Center Gate Mold for the TBGA package variants of the MPC8245 and MPC8250/8255/8260/8265 product families.

Currently, the encapsulation process used on the TBGA package variants of the MPC8245 and MPC8250/8255/8260/8265 product family is the Fine Pitch Glob process. For supply assurance, NXP is adding the Center Gate Mold process to these product families.

Due to the nature of the Center Gate Mold (injection mold) process, the current Dexter FP4451 Dam and Nagase T693/R1001 Glob Filter epoxy will be replaced by the Sumitomo G770SFL Ultra Low Alpha Mold Compound used in established Center Gate Mold products.

Reason for Change

As part of NXP's continuous improvement efforts, this change is being made to support customer supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples availability differs by product - see attached sample plan
See attached sample plan.

Production

Planned first shipment 21-Nov-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
No impact to Form, Fit, Function or Reliability.

Case outline spec is maintained while providing a more dimensionally uniform product. This will be observed as a flatter surface with uniform color.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 23-Sep-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist direct

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